

# OKI semiconductor

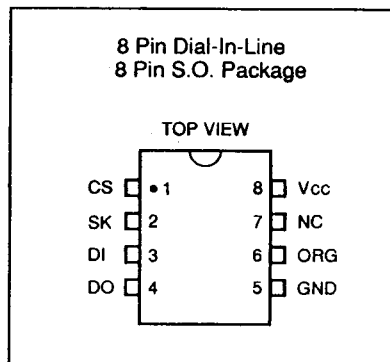
## MSM16831

1,024-Bit SERIAL E<sup>2</sup>PROM

### FEATURES:

- CMOS Floating Gate Technology
- Single +3-volt supply
- Eight pin plastic package
- 64 × 16 or 128 × 8 user selectable serial memory
- Compatible with CATALYST CAT33C101
- Self-timed programming cycle with Auto-erase
- Word and chip erasable
- Operating range 0°C to 70°C
- 10,000 erase/write cycles for each address
- 10 year data retention
- Power-up inadvertent write protection

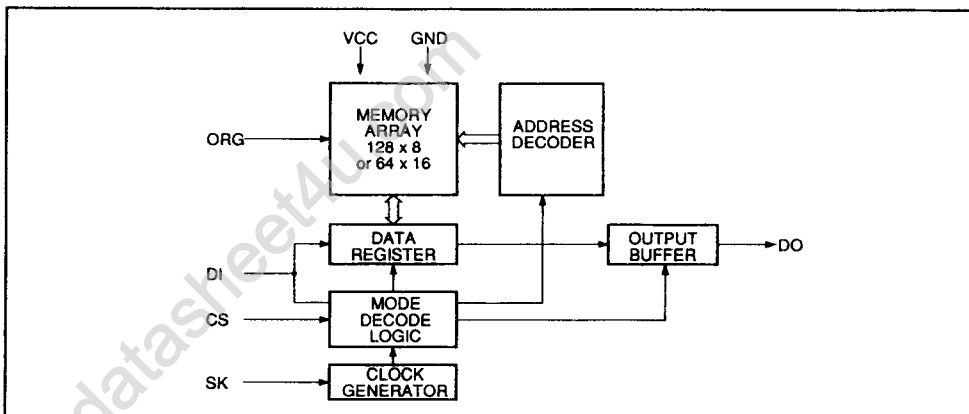
### PIN CONFIGURATION



### PIN FUNCTIONS

CS	Chip Select	ORG	Memory Array Organization Selection Input. When the ORG pin is connected to V <sub>cc</sub> the 64 × 16 organization is selected. When it is connected to ground, the 128 × 8 organization is selected.
SK	Clock Input		
DI	Serial Data Input		
DO	Serial Data Output		
V <sub>cc</sub>	+3 V Power Supply		
NC	No Connection		
GND	Ground		

### BLOCK DIAGRAM



INSTRUCTION SET							Comments
Instruction	Start Bit	Opcode	Address		Data		
			128 x 8	64 x 16	128 x 8	64 x 16	
READ	1	1 0	A <sub>6</sub> -A <sub>0</sub>	A <sub>5</sub> -A <sub>0</sub>			READ Address A <sub>N</sub> -A <sub>0</sub>
ERASE	1	1 1	A <sub>6</sub> -A <sub>0</sub>	A <sub>5</sub> -A <sub>0</sub>			ERASE Address A <sub>N</sub> -A <sub>0</sub>
WRITE	1	0 1	A <sub>6</sub> -A <sub>0</sub>	A <sub>5</sub> -A <sub>0</sub>	A <sub>7</sub> -A <sub>0</sub>	A <sub>15</sub> -A <sub>0</sub>	WRITE Address A <sub>N</sub> -A <sub>0</sub>
EWEN	1	0 0	11xxxxx	11xxxx			Program Enable
EWDS	1	0 0	00xxxxx	00xxxx			Program Disable
ERAL	1	0 0	10xxxxx	10xxxx			Erase All Addresses
WRAL	1	0 0	01xxxxx	01xxxx	A <sub>7</sub> -A <sub>0</sub>	A <sub>15</sub> -A <sub>0</sub>	Program All Addresses

**Power-On Data Protection Circuitry:** During power-up, all modes of operation except READ mode are inhibited until V<sub>cc</sub> reaches a level of approximately 2.5 V. During power-down, the source data protection circuitry inhibits all modes except READ when V<sub>cc</sub> falls below the voltage range of approximately 2.5 V.

**ELECTRICAL CHARACTERISTICS**  
**ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Condition	Value	Unit
Supply Voltage	V <sub>CC</sub>	T <sub>a</sub> = 25°C	-0.3 ~ 7	V
Input Voltage	V <sub>I</sub>		-0.3 ~ V <sub>CC</sub> + 0.3	V
Output Voltage	V <sub>O</sub>		-0.3 ~ V <sub>CC</sub> + 0.3	V
Storage Temperature	T <sub>STG</sub>		-55 ~ +150	°C

Note: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as recommended. Exposure to ABSOLUTE MAXIMUM RATINGS for extended periods may affect device reliability.

**RECOMMENDED OPERATING RANGE**

Parameter	Symbol	Range	Unit
Supply Voltage	V <sub>CC</sub>	3 ± 10%	V
Temperature Range	T <sub>a</sub>	0 ~ 70	°C
Data Hold Temperature	T <sub>a</sub>	0 ~ 70	°C

**DC CHARACTERISTICS**

(V<sub>CC</sub> = 2.7V to 3.3V, T<sub>a</sub> = 0°C ~ 70°C, unless otherwise specified.)

Parameter	Symbol	Condition	Min	Max	Unit
Supply Voltage	V <sub>CC</sub>		2.7	3.3	V
Power Supply Current	I <sub>CC1</sub>	Write	V <sub>CC</sub> = 3.0V CS = 3.0V DI = SK = 0.0V DO = OPEN	2	mA
		Read		0.5	
	I <sub>CC2</sub>	V <sub>CC</sub> = 3.3 V CS = 0 DO = ORG = OPEN DI = 0 SK = 0		50	μA
"L" Input Voltage	V <sub>IL</sub>		-0.1	0.3	V
"H" Input Voltage	V <sub>IH</sub>		V <sub>CC</sub> -0.3	V <sub>CC</sub> +1	V
"L" Output Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 10 μA		0.3	V
"H" Output Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -10 μA	V <sub>CC</sub> -0.3		V
Input Leakage Current	I <sub>LI</sub>	V <sub>in</sub> = V <sub>CC</sub> + 0.1V		10	μA
Output Leakage Current	I <sub>LO</sub>	V <sub>out</sub> = V <sub>CC</sub> CS = 0		10	μA

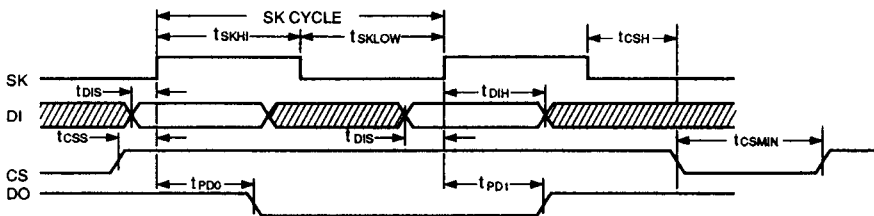
**CHARACTERISTICS**

(V<sub>CC</sub> = 2.7V to 3.3V, T<sub>a</sub> = 0°C ~ 70°C)

Parameter	Description	Test Condition	Min	Typ	Max	Unit
t <sub>CSS</sub>	CS Set up Time		0.2			μs
t <sub>CSH</sub>	CS Hold Time		0			μs
t <sub>DIS</sub>	DI Setup Time		0.4			μs
t <sub>DIH</sub>	DI Hold Time		0.4			μs
t <sub>PD1</sub>	Output Delay to 1	C <sub>L</sub> = 100pF See Note 1			2	μs
t <sub>PD0</sub>	Output Delay to 0				2	μs
t <sub>HZ</sub>	Output Delay to HiZ				0.4	μs
t <sub>EW</sub>	Erase / Write Pulse Width				20	ms
t <sub>CSMIN</sub>	Min CS Low Time			1		μs
t <sub>SKHI</sub>	Min SK High Time			1		μs
t <sub>SKLOW</sub>	Min SK Low Time			1		μs
t <sub>SV</sub>	Output Delay to Status Valid	C <sub>L</sub> = 100 pF			1	μs
SK <sub>MAX</sub>	Maximum Frequency			0	250	kHz

Note 1: All timing measurements are defined at the point of signal crossing V<sub>CC</sub> / 2.

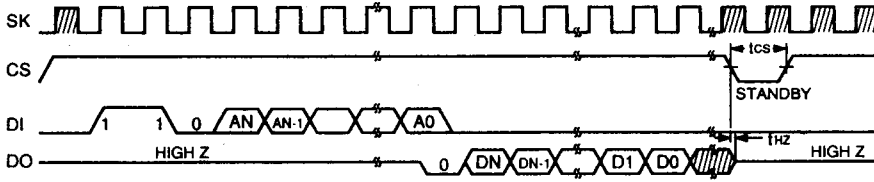
**Synchronous Timing**



**DEVICE OPERATION**

The MSM16831 has 7 instructions that allow it to read, erase, or write. Each instruction consists of a start bit logical 1, an opcode field (2 bits or 4 bits) and an address field (6 or 7 bits). The DO pin is a multiplexed pin. It is used as Data Out during the Read mode. It can also be used as a Ready Busy status indicator in programming mode. In all the other modes DO is tri-stated. During power-up, all modes of operation are disabled and the device comes up in a program disabled state. An EWEN instruction must be issued before starting to program. At power-down, when V<sub>CC</sub> falls below a level of approximately 2.5 V, the data protection circuitry inhibits operation, except READ mode, and an EWDS instruction is executed internally.

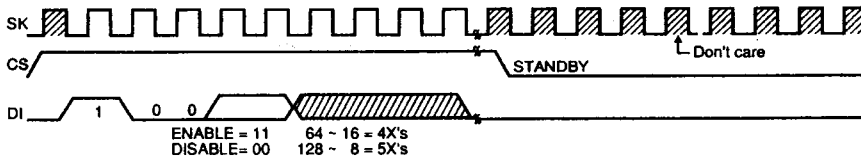
**READ**



Organization	$A_N$	$D_N$
128 × 8	$A_6$	$D_7$
64 × 16	$A_5$	$D_{15}$

The READ instruction reads the contents of the addressed register. It outputs data serially on the DO pin. After the instruction is decoded, a dummy bit (logical 0) precedes the output data string.

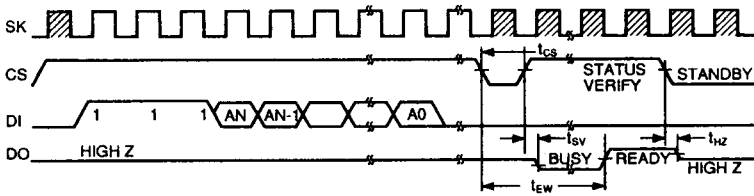
**EWEN/EWDS (Erase Write Enable/Erase Write Disable)**



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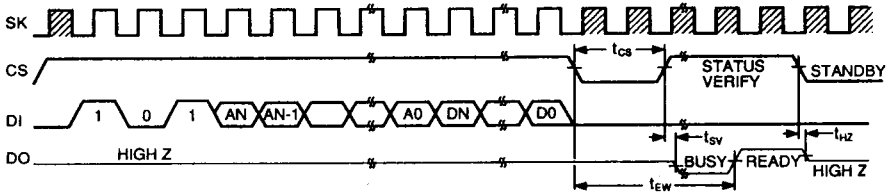
After power-up and before starting any programming instruction the EWEN instruction must be issued. Once it is issued, it remains active until an EWDS instruction takes place. The EWDS instruction prevents any accidental programming of the part. The READ instruction is independent from the EWEN and EWDS instructions.

**ERASE**



After an ERASE instruction is shifted in, CS is dropped low. This sets the beginning of the self timed erase sequence. If CS is then brought high (after observing  $t_{cs}$  spec) the DO pin acts as a status indicator. It remains low so long as the chip is programming. It goes high after all the bits of the addressed register are set to a logical 1.

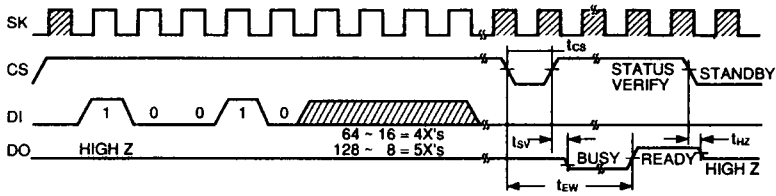
**WRITE**



After a WRITE instruction is shifted in with the corresponding 8 bits or 16 bits of data, CS is dropped low. This sets the beginning of the self timed programming sequence. If CS is brought high during the programming time (after observing the  $t_{cs}$  specification), the DO pin acts as a status indicator – it remains low so long as the chip is programming. It goes high after all the bits of the addressed register are set to their proper value. With the MSM16831 it is NOT necessary to erase a memory location before the WRITE instruction.

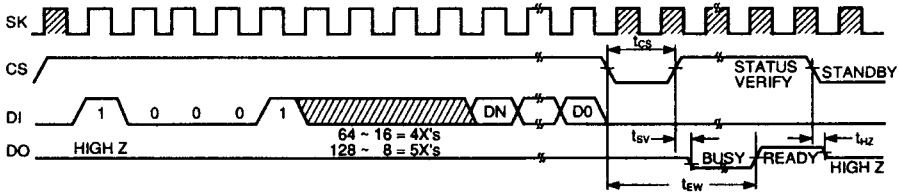
Organization	AN	DN
128 × 8	A6	D7
64 × 16	A5	D15

**ERAL (Erase All)**



The ERAL instruction erases the whole chip. Except for its different opcode, the ERAL instruction is identical to the ERASE instruction.

**WRAL (Write All)**



The WRAL instruction writes to all the registers simultaneously. All the registers must be erased before a WRAL operation. Except for its different opcode, the WRAL instruction is identical to the WRITE instruction.